

•FEATURE

- 1. Small size High saturation current
- 2. Operating Temperature -40 ~ 125°C
- 3. Compliant with AEC-Q200

APPLICATION

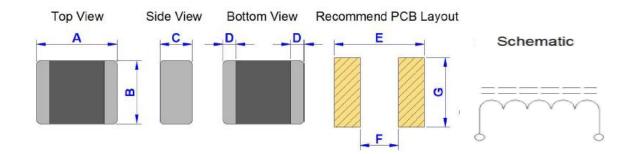
Portable Device, Smart Phone, Tablet PC, LTE Module, Hard Disk of Ultrabook



•ORDERING INFORMATION

<u>WCJ</u>	201608	<u>U</u>	<u>-1R0</u>	T	<u>Q</u>
Series	Dimension	Material code	Impedance	Tolerance	AEC-Q
	(L*W*H)	(A, B, L)	(Ω)	M=±20%, Y=±30	

•SHAPE AND DIMENSION



•SPECIFICATION

Unit: mm (inch)

TYPE	А	В	С	D	E	F	G
201608(0806)	2.00±0.20	1.60±0.20	0.80	0.50±0.30	0.80 ref.	0.70 ref.	1.80 ref.
201610(0806)	2.00±0.20	1.60±0.20	1.00	0.50±0.30	0.55 ref.	0.90 ref.	1.60 ref.
252010(1008)	2.50±0.20	2.00±0.20	1.00	0.60±0.30	0.80 ref.	1.20 ref.	2.00 ref.
252012(1008)	2.50±0.20	2.00±0.20	1.20	0.60±0.30	0.80 ref.	1.20 ref.	2.00 ref.
322512(1210)	3.20±0.30	2.50±0.30	1.20	0.50±0.30	0.75 ref.	1.70 ref.	2.50 ref.



•ELECTRICAL CHARACTERISTICS

	Inductance	DCR	DCR	lsat	Irms
Part Number		(mΩ)	(mΩ)	(mA)	(mA)
	(uH)	Тур.	Max.	Тур.	Тур.
WCJ201608A-1R0M	1.00	76.0	87.0	2800	2700
WCJ201608A 1R5M	1.50	102	115	2300	2400

Inductance test Freq.: 2MHz / 0.2V

M=Tolerance = $\pm 20\%$

Isat: For Inductance drop 30% from its value without current.

Irms: For a 40°C temperature rise from 25°C ambient.

	Inductance	DCR	DCR	lsat	Irms
Part Number		(mΩ)	(mΩ)	(mA)	(mA)
	(uH)	Тур.	Max.	Тур.	Тур.
WCJ201610A-R24M	0.24	28.0	40.0	6000	4500
WCJ201610A-R33M	0.33	40.0	48.0	5500	3800
WCJ201610A-R47M	0.47	44.0	54.0	5000	3600
WCJ201610A-R56M	0.56	46.0	59.0	4600	3300
WCJ201610A-R68M	0.68	55.0	72.0	4200	3000
WCJ201610A-1R0M	1.00	81.0	96.0	3400	2300
WCJ201610A-1R5M	1.50	122	150	2800	2000
WCJ201610A-2R2M	2.20	170	204	2400	1600

Inductance test Freq.: 2MHz / 0.2V

M=Tolerance = $\pm 20\%$

Isat: For Inductance drop 30% from its value without current.

Irms: For a 40°C temperature rise from 25°C ambient.

Part Number	Inductance	DCR (mΩ)	DCR (mΩ)	lsat (mA)	Irms (mA)
	(uH)	Тур.	Max.	Тур.	Тур.
WCJ201610B-R24M	0.24	23.0	30.0	6000	4400
WCJ201610B-R47M	0.47	34.0	41.0	4500	3300
WCJ201610B-R68M	0.68	44.0	53.0	3600	2900
WCJ201610B-1R0M	1.00	60.0	72.0	3200	2500
WCJ201610B-2R2M	2.20	142.0	170	2100	1700

Inductance test Freq.: 2MHz / 0.2V

M=Tolerance = $\pm 20\%$

Isat: For Inductance drop 30% from its value without current.

Irms: For a 40°C temperature rise from 25°C ambient.



	Inductance	DCR	DCR	lsat	Irms
Part Number		(mΩ)	(mΩ)	(mA)	(mA)
	(uH)	Тур.	Max.	Тур.	Тур.
WCJ252010B-R33M	0.33	25.0	31.0	6000	4400
WCJ252010B-R47M	0.47	29.0	35.0	4700	3900
WCJ252010B-R68M	0.68	40.0	48.0	4000	3500
WCJ252010B-1R0M	1.00	54.0	65.0	3600	3000
WCJ252010B-1R5M	1.50	78.0	94.0	3300	2400
WCJ252010B-2R2M	2.20	100	120	2700	2100

Inductance test Freq.: 2MHz / 0.2V

M=Tolerance = $\pm 20\%$

Isat : For Inductance drop 30% from its value without current.

Irms : For a 40°C temperature rise from 25°C ambient.

	Inductance	Tolerance	DCR	DCR	Isat	Irms
Part Number			(mΩ)	(mΩ)	(mA)	(mA)
	(uH)	(T)	Тур.	Max.	Тур.	Тур.
WCJ252012L-R24T	0.24	Y	16.0	21.0	9000	5400
WCJ252012L-R33T	0.33	М	20.0	24.0	7100	4800
WCJ252012L-R47T	0.47	М	24.0	29.0	6000	4500
WCJ252012L-R68T	0.68	М	27.0	36.0	5400	4000
WCJ252012L-1R0T	1.00	М	38.0	46.0	4600	3500
WCJ252012L-1R5T	1.50	М	56.0	67.0	3500	3000
WCJ252012L-2R2T	2.20	М	76.0	91.0	3100	2500

Inductance test Freq.: 1MHz / 1V

T=Tolerance = $M\pm 20\%$, Y= $\pm 30\%$

Isat : For Inductance drop 30% from its value without current.

Irms : For a 40°C temperature rise from 25°C ambient.

Part Number	Inductance	DCR (mΩ)	DCR (mΩ)	lsat (mA)	Irms (mA)
	(uH)	Тур.	Max.	Тур.	Тур.
WCJ322512A-R47M	0.47	21.0	27.0	9000	5800
WCJ322512A-1R0M	1.00	34.0	42.0	6300	4200
WCJ322512A-1R5M	1.50	58.0	68.0	4500	3200
WCJ322512A-2R2M	2.20	75.0	85.0	4000	2700

Inductance test Freq.: 2MHz / 0.2V

M=Tolerance = $\pm 20\%$

Isat : For Inductance drop 30% from its value without current.

Irms : For a 40°C temperature rise from 25°C ambient.



•RELIABILITY

Test Item		Specification		
Dimension	Actual Size			Meet Spec
Thermal Shock (Temperature Cycle)	Temperature: -40 ~ +12 Cycle: 100 Cycles (pow	•	30 min. each	Elec. no variation Appearance no deformation
Humidity Resistance	Humidity: 90% ~ 95% F Temperature: 60 ± 2°C		ırs	Elec. no variation Appearance no deformation
High Temperature	Temperature: 125 ± 2°0 Testing Time: 96 ± 2 H			Elec. no variation Appearance no deformation
Low Temperature	Temperature: -40 ± 2°0 Time: 96 ± 2 Hours	2		Elec. no variation Appearance no deformation
	Temperature	Humidity	Time	
Tomoroture and	25°C	90% ~ 95% RH	3.0 Hr	
Temperature and	55°C	95% ~ 96% RH	5.0 Hr	Elec. no variation
Humidity Cycle	25°C	90% ~ 95% RH	3.0 Hr	Appearance no deformation
	Cycle: 20 Cycles		·	
Vibration	Frequency: 10Hz ~ 55F Direction: X, Y, Z, Time		1	Elec. no variation Appearance no deformation
Solderability	Go through real SMT IF The profile like our sug Preheat: 160 ± 10°C (9 Peak: 245 ± 5°C Peak Time: 50 Sec. / u	Elec. no variation Appearance no deformation		
Soldering Heat Resistance	Preheat: 160 ± 10°C (9 Solder: Sn / Ag / Cu (Pl Solder Temp.: 260 ± 5°	b Free)	5	Elec. no variation Appearance no deformation
Iron Solder Heat Resistance	Solder Temp.: 350 ± 5° Flux: Rosin, Time: 3 ±			Elec. no variation Appearance no deformation
Bending Strength	Unit : m	10 x 10 1	R : 0.5	Elec. no variation Appearance no deformation
Flexure Strength	Unit : mm 1.6	Elec. no variation Appearance no deformation		
Terminal Strength	X			Elec. no variation Appearance no deformation
High-Voltage	100 V DC between core	Elec. no variation Appearance no deformation		
Load life	Temperature: 25 ± 3°C Load: Allowed DC Curr		Hours	Elec. no variation Appearance no deformation



•TEST EQUIPMENT

- 1. HP4284A, HP42841A L , Q , DCR , IDC
- 2. HP8753D Network analyzer SRF

•Operating & Storage Condition

- 1. Operating Temp: -40 ~ +125°C (Including self temperature rise)
- 2. Storage Temp: a. -10 ~ +45°C, 50 ~ 60% RH (Product with taping)

b. -40 ~ +125°C (On board)

3. Storage Life Time: 6 Month (Less than 40°C and 60% RH)

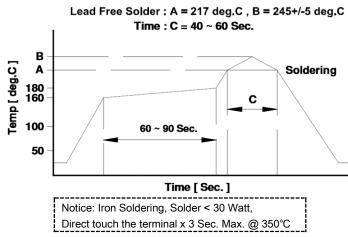
Standard Atmosphere Conditions:

Ambient Temp: 20 ±15°C; Relative Humidity: 65 ±20%

If there may be any doubt on the result, measurement shall be made within the following limits :

Ambient Temp: 25 ±5°C; Relative Humidity: 75 ±10%

•RECOMMEND IR REFLOW CURVE: (TIME: Second)



•ATTENTION & CAUTION

- * Keep out of: Splashing water or salt water
- * Avoid: Toxic Gas (Hydrogen sulfide, Sulfurous acid, Chlorine, Ammonia)
- * Vibrations or shocks which exceed the specified condition, Dew condense
- * Layout near the edge of PCB
- * Over flexure after SMT mounting & PCBA
- * Pin foot or SMD pad solder ability: Pb free type is best within 6 months after delivery
- * Humidity sensitive, IPC/JEDEC J-STD-020 MSL if over Level 1, recommend bake 30 mins@150°C before PCBA
- * Caution for human life relative applications: PLS contact & consult with AiT team in design stage.



Care Note for Use:

(1) Storage Condition:

Temperature 25 to 35°C, Humidity 45 to 60% RH

(2) Use Temperature:

a. Minimum Temperature: -40°C Ambient temperature of this product.

b. Maximum Temperature: +125°C The value of temperature including ambient and temperature rise of this product.

c. Reliability test temperature range from -40 ~ +125°C

d. However, this is not meant as temperature grade guarantee for UL.

(3) Model:

When this product was used in a similar or as new product to the original one, sometimes it might be unable to satisfy the specifications due to difference in condition of usage.

(4) Drop:

If this product suffered mechanical stress such as drop, characteristics may become poor (due to damage on coil / bobbin / ferrite \dots etc.)

Never use such stressed product.

Care Note for Safety:

(1) Provision to Abnormal Condition:

This product itself does not have any protective function in abnormal condition such as overload, shortcircuit and open-circuit conditions, etc.

Therefore, it shall be confirmed from the end product that there is no risk of smoking, fire, dielectric withstand voltage insulation resistance, etc. in abnormal conditions to provide protective devices and /or protection circuit in the end product.

(2) Temperature Rise:

Temperature rise on this product depends on the installation condition on end products.

It shall be confirmed on the actual end product that temperature rise of this product is within the specified temperature class limit.

(3) Dielectric Strength:

Dielectric withstanding test with higher voltage than specific value will damage insulating material and shorten its life.

(4) Water:

This product must not be used in wet condition resulted from water, coffee or any liquid contact because insulation strength becomes very low under such condition.

(5) Potting:

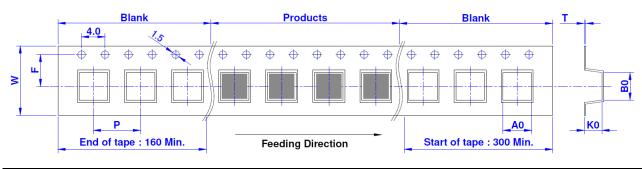
If this product is potted in some compound, coating material of magnet wire might be occasionally damaged. Please ask us if you intend to pot this product.

(6) Detergent:

Please consult AiT Semi immediately once under such circumstances because product reliability confirmation etc. is needed when this product come in contact with these chemicals.

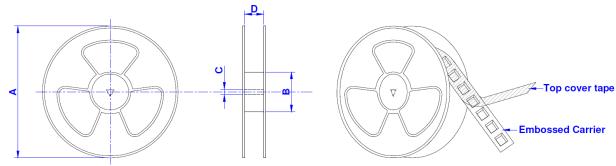


•TAPE DIMENSION: mm



SIZE/mm	W	P	A0	B0	Т	F
201608	8.0	4.0	1.80	1.15	0.22	3.5
201610	8.0	4.0	1.80	1.15	0.22	3.5
252010	8.0	4.0	2.25	1.35	0.22	3.5
252012	8.0	4.0	2.25	1.35	0.22	3.5
322512	8.0	4.0	2.80	1.35	0.22	3.5

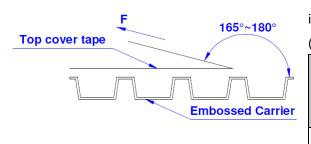
•REEL DIMENSION: mm



SIZE / mm	REEL SIZE	A	В	С	D	QTY/REEL
201608	7" x 8mm	178	60	13	8.5	3000 PCS
201610	7" x 8mm	178	60	13	8.5	3000 PCS
252010	7" x 8mm	178	60	13	8.5	3000 PCS
252012	7" x 8mm	178	60	13	8.5	3000 PCS
322512	7" x 8mm	178	60	13	8.5	3000 PCS



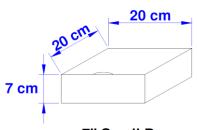
•TEARING OFF FORCE:

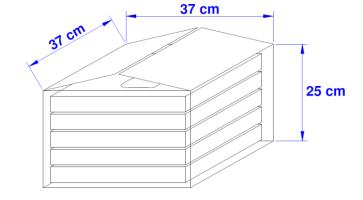


The force for tearing off cover tape is 10 to 130 grams in the arrow direction under the following conditions (referenced ANSI/EIA - 481 - D - 2008 of 4.11stadnard).

Room	Room	Room Atm.	Tearing
Temp.	Humidity		Speed
(°C)	(%)	(hPa)	(mm/min)
5 ~ 35	45 ~ 85	860~1060	300

•BOX PACKAGE: cm





7" Small Box

Large Box

SIZE / mm	Reels in Small Box	Small Box in Large Box
201608	5	8
201610	5	8
252010	5	8
252012	5	8
322512	5	8



IMPORTANT NOTICE

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